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SAMTEC RELEASES MICRO BACKPLANE INTERFACE DESIGN GUIDE

Samtec has released its new Micro Backplane Design Guide detailing how the company's high Speed and High Density Board-to-Board and Panel-and-I/O interface solutions can be used for add-on boards, creative packaging solutions, and for increasing I/O density.

Board-to-Board solutions include perpendicular and co-planar applications for high speed edge card (HSEC8 Series) and Samtec's rugged two-piece EdgeRate™ connector system (ERM8/ERF8 Series.) High density solutions are addressed with SEARAY™ (SEAM/SEAF Series) open pin field arrays, while Q2™ integrated ground plane connectors (QMS/QFS Series) address traditional power and ground applications within high speed interconnects.

Creative I/O solutions are shown that can increase panel density and/or achieve I/O flexibility. Coax cable and high speed flex jumper solutions can route signals from the back of the box to the front panel: They can also be used to by-pass traditional backplanes. Samtec's True75™ BNC and micro backplane solutions for 3G SDI broadcast video are also illustrated.

Full engineering support for these high speed systems including design, development, simulation, and testing is also available via Samtec's Signal Integrity group.

For your copy of Samtec's new Micro Backplane guide, contact: Samtec, Inc. • P.O. Box 1147 • New Albany, IN 47151-1147 • Phone: 1-800-SAMTEC-9 or 812-944-6733 • Fax: 812-948-5047 • Internet: http://www.samtec.com • E-mail: info@samtec.com.